N-Channel 8 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I_D (A)[a]	Q_g (Typ.)
8	0.0094 at V_{GS} = 4.5 V	12	15 nC
	0.0105 at V_{GS} = 2.5 V	12	
	0.0125 at V_{GS} = 1.8 V	12	
	0.0180 at V_{GS} = 1.5 V	12	
	0.0360 at V_{GS} = 1.2 V	12	

FEATURES

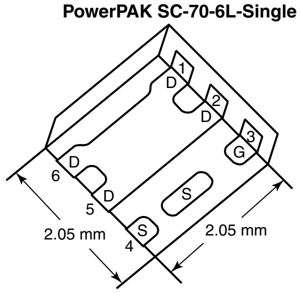
- **Halogen-free According to IEC 61249-2-21 Definition**
- TrenchFET® Power MOSFET
- Thermally Enhanced PowerPAK® SC-70 Package
  - Small Footprint Area
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

Pb-free RoHS COMPLIANT HALOGEN FREE

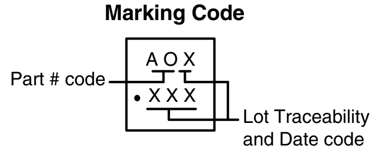
APPLICATIONS

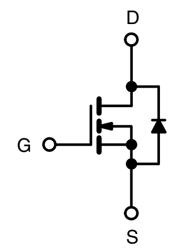
- Load Switch for Portable Applications such as Smart Phones, Tablet PCs and Mobile Computing
  - Low Voltage Gate Drive
  - Low Voltage Drop
  - Power Switch for ICs

PowerPAK SC-70-6L-Single



Marking Code





N-Channel MOSFET

Ordering Information: SiA436DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	8	V
Gate-Source Voltage		V_{GS}	± 5	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	12[a]	A
	T_C = 70 °C		12[a]	
	T_A = 25 °C		12[a, b, c]	
	T_A = 70 °C		12[a, b, c]	
Pulsed Drain Current (t = 300 µs)		I_{DM}	50	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	12[a]	
	T_A = 25 °C		2.9[b, c]	
Maximum Power Dissipation	T_C = 25 °C	P_D	19	W
	T_C = 70 °C		12	
	T_A = 25 °C		3.5[b, c]	
	T_A = 70 °C		2.2[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature)[d, e]			260	

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[b, f]	t ≤ 5 s	R_{thJA}	28	36	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	5.3	6.5	

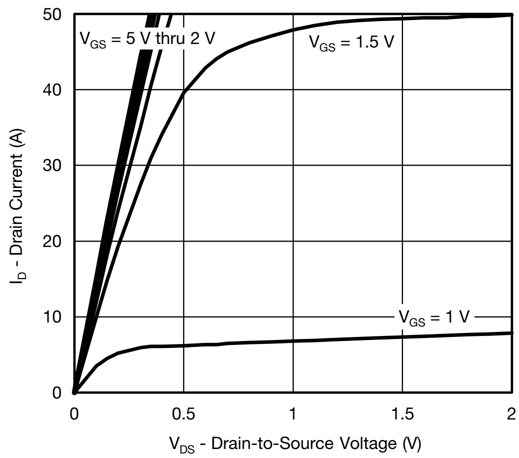
Notes:
a. Package limited
b. Surface mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. See solder profile (www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
f. Maximum under steady state conditions is 80 °C/W.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	8			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA		11		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 2.5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D = 250 µA	0.35		0.8	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 5 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 8 V, V_{GS} = 0 V			1	µA
		V_{DS} = 8 V, V_{GS} = 0 V, T_J = 55 °C			10	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ 5 V, V_{GS} = 4.5 V	20			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 4.5 V, I_D = 15.7 A		0.0078	0.0094	Ω
		V_{GS} = 2.5 V, I_D = 14.9 A		0.0087	0.0105	
		V_{GS} = 1.8 V, I_D = 13.6 A		0.0104	0.0125	
		V_{GS} = 1.5 V, I_D = 2.5 A		0.0120	0.0180	
		V_{GS} = 1.2 V, I_D = 1.5 A		0.0180	0.0360	
Forward Transconductance[a]	g_{fs}	V_{DS} = 4 V, I_D = 15.7 A		70		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 4 V, V_{GS} = 0 V, f = 1 MHz		1508		pF
Output Capacitance	C_{oss}			535		
Reverse Transfer Capacitance	C_{rss}			321		
Total Gate Charge	Q_g	V_{DS} = 4 V, V_{GS} = 5 V, I_D = 15.7 A		16.8	25.2	nC
		V_{DS} = 4 V, V_{GS} = 4.5 V, I_D = 15.7 A		15	23	
Gate-Source Charge	Q_{gs}			1.7		
Gate-Drain Charge	Q_{gd}			0.9		
Gate Resistance	R_g	f = 1 MHz	0.5	2.5	5	Ω
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 4 V, R_L = 0.4 Ω I_D ≅ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		11	20	ns
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(off)}$			30	45	
Fall Time	t_f			8	16	
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 4 V, R_L = 0.4 Ω I_D ≅ 10 A, V_{GEN} = 5 V, R_g = 1 Ω		10	20	
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(off)}$			30	45	
Fall Time	t_f			8	16	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			12	A
Pulse Diode Forward Current	I_{SM}				50	
Body Diode Voltage	V_{SD}	I_S = 10 A, V_{GS} = 0 V		0.73	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 10 A, di/dt = 100 A/µs, T_J = 25 °C		10	20	ns
Body Diode Reverse Recovery Charge	Q_{rr}			1	4	nC
Reverse Recovery Fall Time	t_a			4		ns
Reverse Recovery Rise Time	t_b			6		

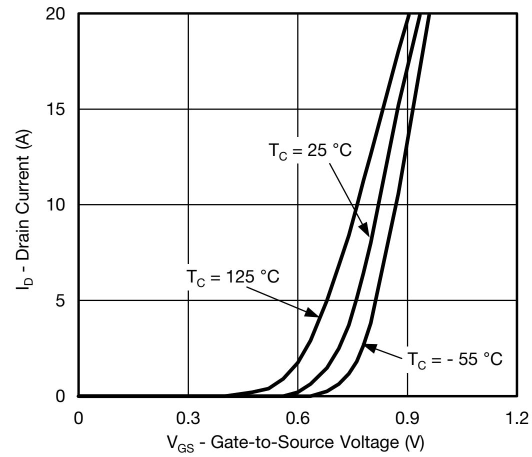
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

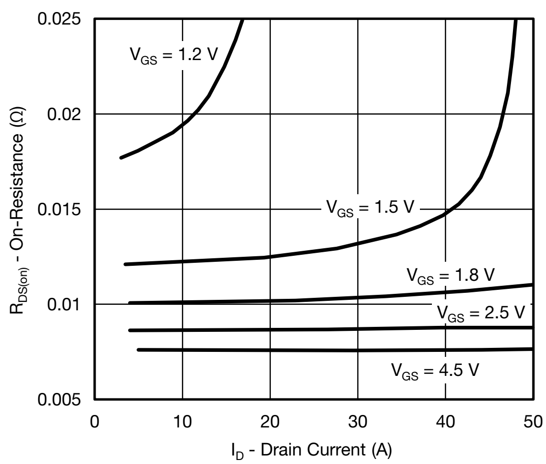
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



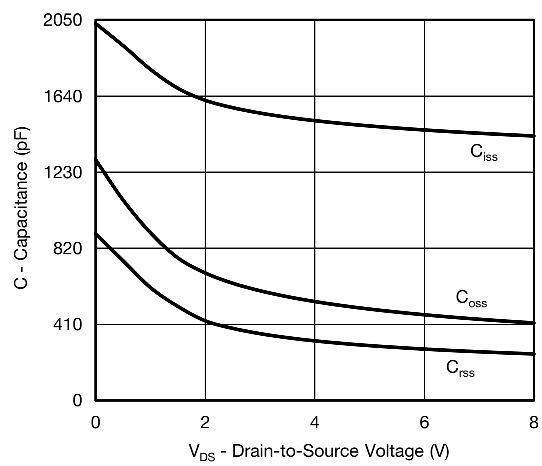
Output Characteristics



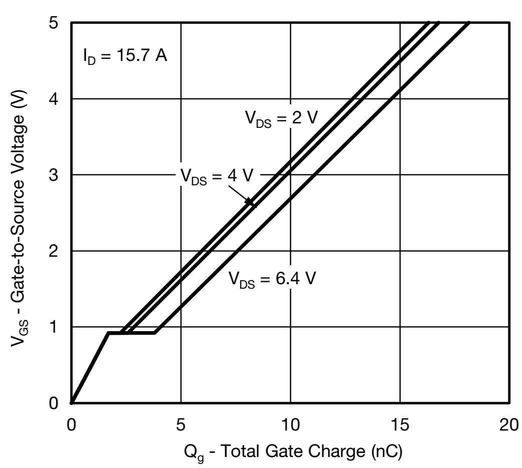
Transfer Characteristics



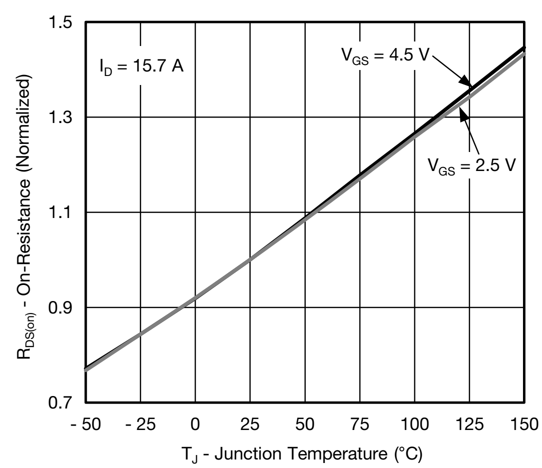
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

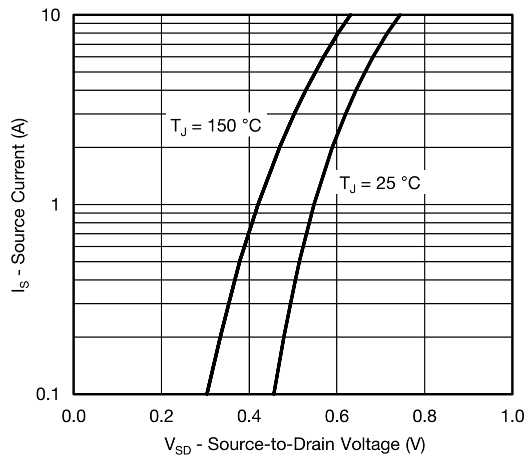


Gate Charge

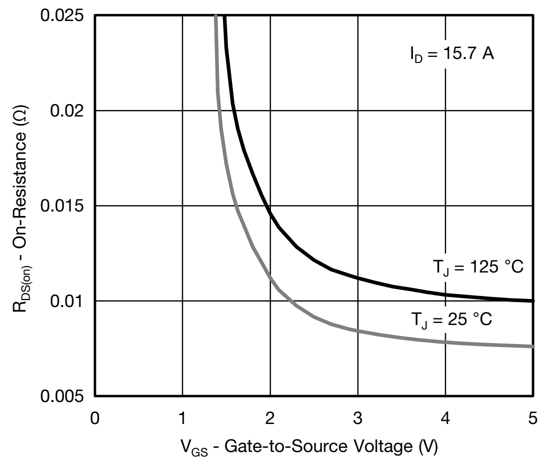


On-Resistance vs. Junction Temperature

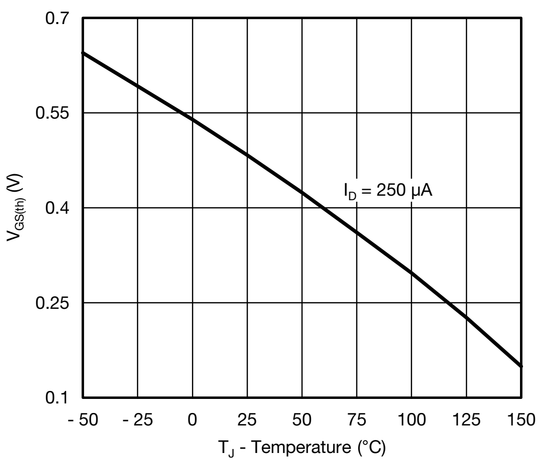
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



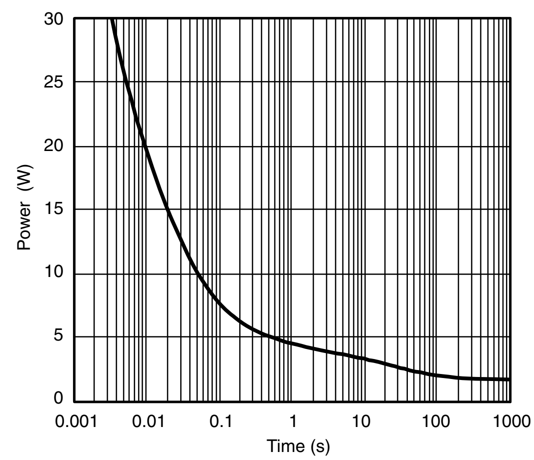
Source-Drain Diode Forward Voltage



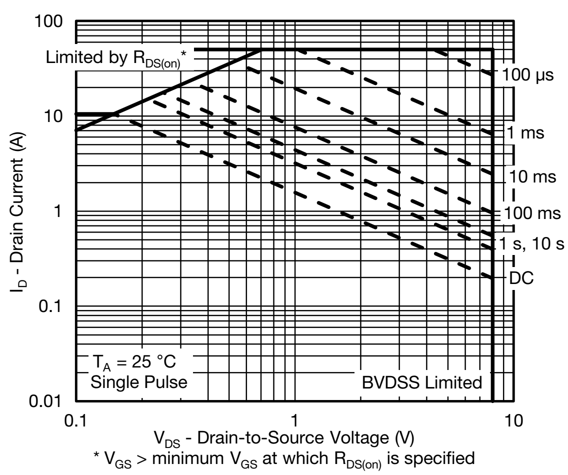
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

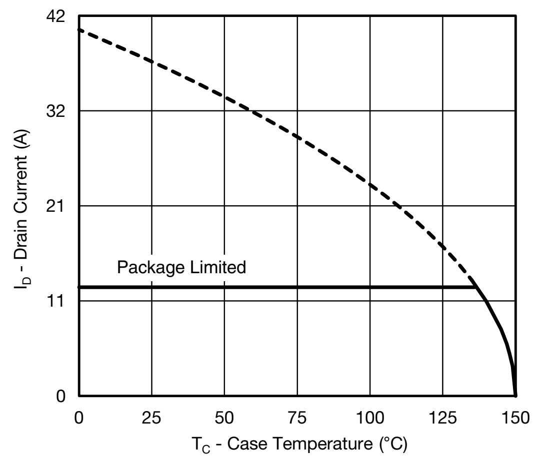


Single Pulse Power (Junction-to-Ambient)

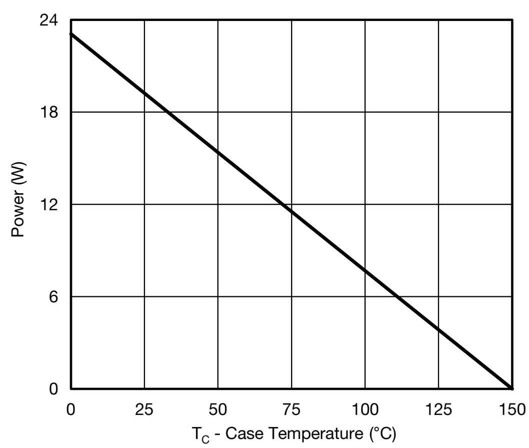


Safe Operating Area, Junction-to-Ambient

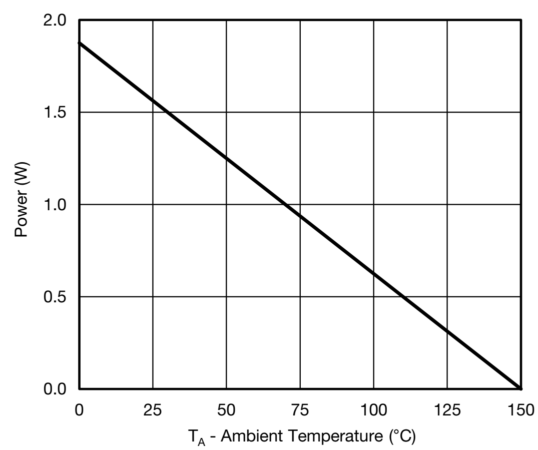
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



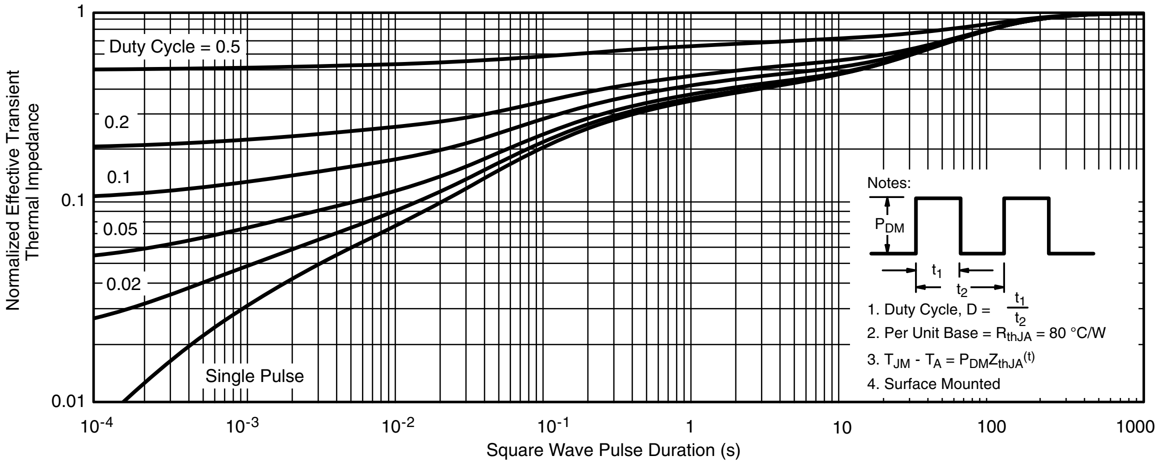
Power Derating, Junction-to-Case



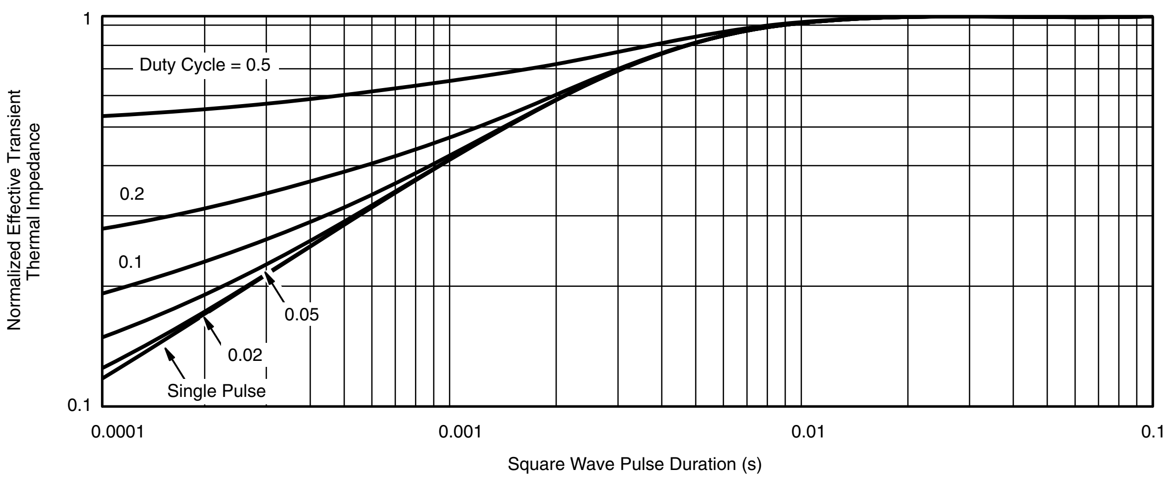
Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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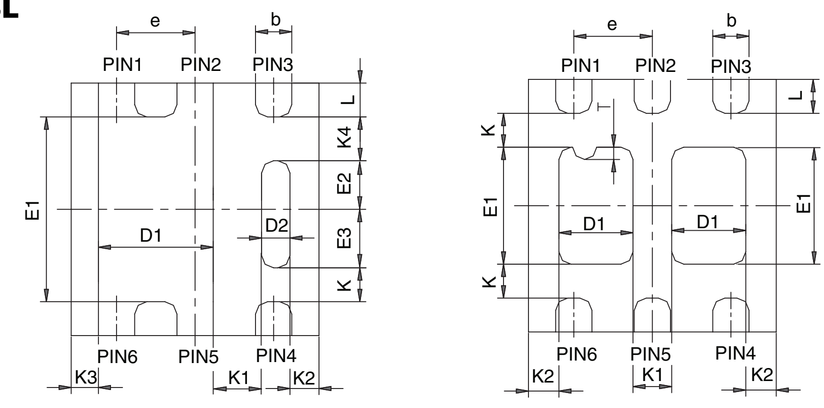
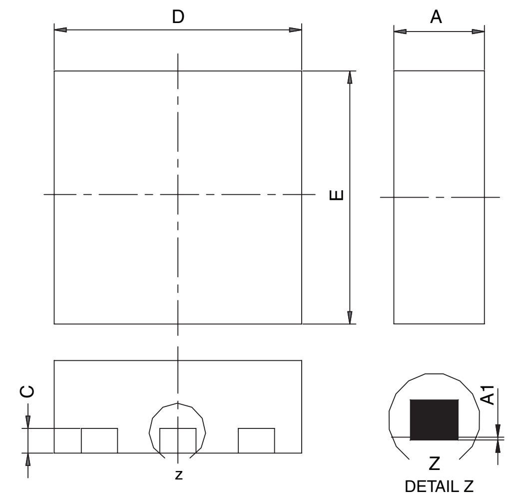
PowerPAK® SC70-6L



BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL

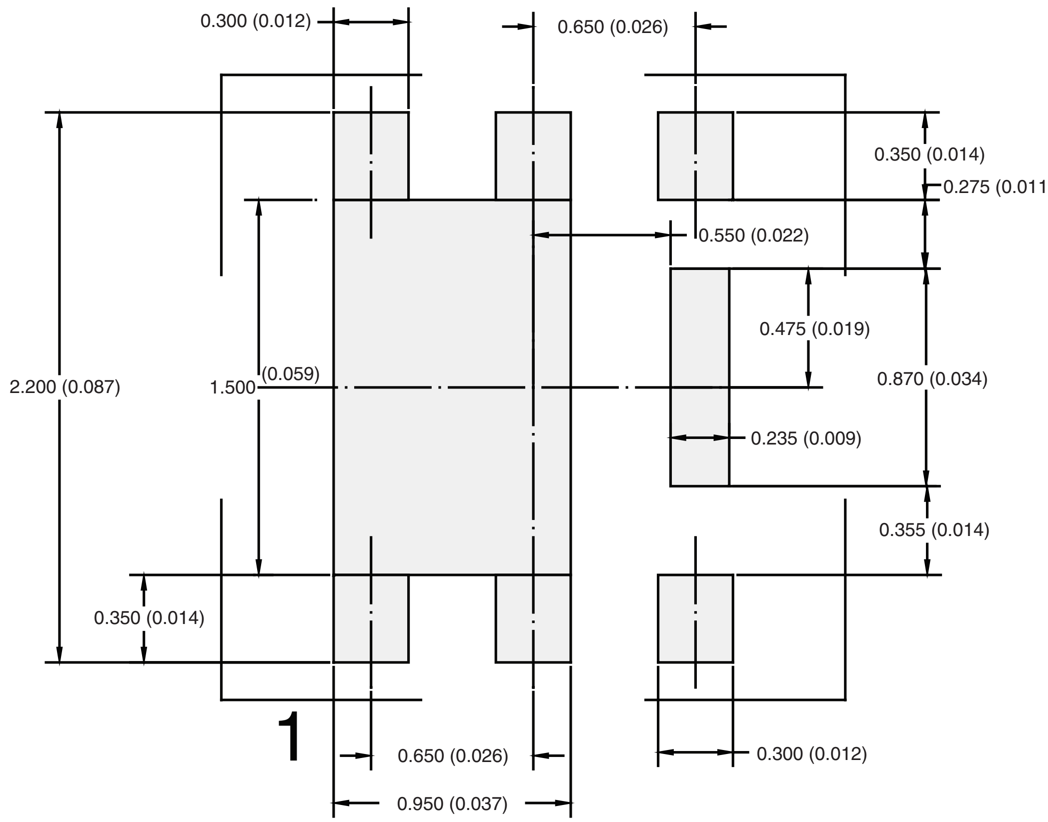


Notes:
1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006

ECN: C-07431 − Rev. C, 06-Aug-07
DWG: 5934

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single



Dimensions in mm/(Inches)

Return to Index

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